



US 20240237152A9

(19) **United States**
(12) **Patent Application Publication**
Kröner et al.

(10) **Pub. No.: US 2024/0237152 A9**
(48) **Pub. Date: Jul. 11, 2024**
CORRECTED PUBLICATION

(54) **PTC HEATING DEVICE AND METHOD OF MANUFACTURING THE SAME**

B23K 20/10 (2006.01)
F24H 9/1863 (2006.01)

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(52) **U.S. Cl.**
CPC *H05B 3/267* (2013.01); *B23K 20/002* (2013.01); *B23K 20/10* (2013.01); *F24H 9/1872* (2013.01); *F24H 2250/04* (2013.01); *H05B 2203/016* (2013.01); *H05B 2203/017* (2013.01); *H05B 2203/02* (2013.01)

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(21) Appl. No.: **18/381,900**

(57) **ABSTRACT**

(22) Filed: **Oct. 19, 2023**

A PTC heating device has a frame surrounding an accommodation space, at least one PTC element accommodated in the accommodation space, and conductor elements, which are connected to the PTC element in an electrically conductive manner and enclose the PTC element between them. Each of the conductor elements is surrounded by a frame segment. The frame segments are welded together to enclose the PTC element in the accommodation space. In the method according to the invention, injection molded plastic frame segments having interacting connection segments are connected to conductor elements. At least one PTC element is then introduced between the frame segments. The frame segments are approached to each other until the connection segments abut against each other. The connection segments are then melted. As a result of this melting, the frame segments are approached further to each other until the conductor elements abut against the PTC element.

Prior Publication Data

(15) Correction of US 2024/0138029 A1 Apr. 25, 2024
See (22) Filed
See (30) Foreign Application Data

(65) US 2024/0138029 A1 Apr. 25, 2024

Foreign Application Priority Data

Oct. 21, 2022 (DE) 10 2022 127 875.1

Publication Classification

(51) **Int. Cl.**
H05B 3/26 (2006.01)
B23K 20/00 (2006.01)

